EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	174199	(flipchip (flip adj chip) (semiconductor die dice chip element mocroelectronic ic (integrated adj circuit)) with (bump ball bga))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/23 10:20
L2	7945	(caposer interpos$4 intermediat$4) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/23 10:21
L3	2874	(land$4 pad electrode contact terminal) with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/23 10:21
L4	1677	3 with (substrate carrier board motherboard packag$4 pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/23 10:22
L5	1462	3 with (substrate carrier board motherboard pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/23 10:22
L6	548	packag$ same 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/23 10:23